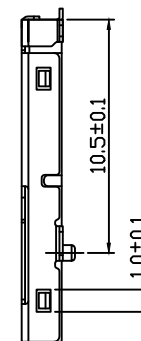
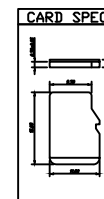
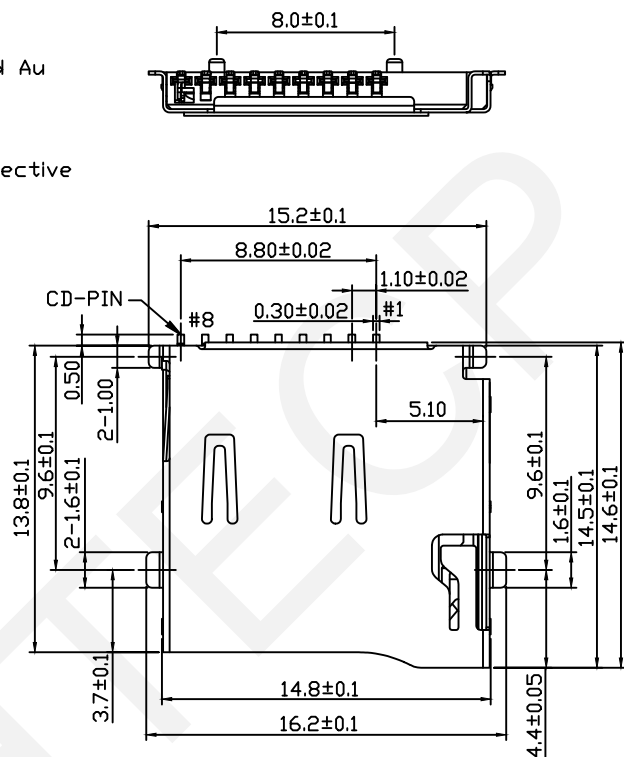
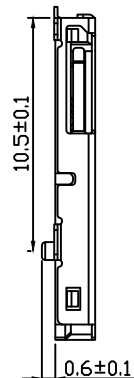
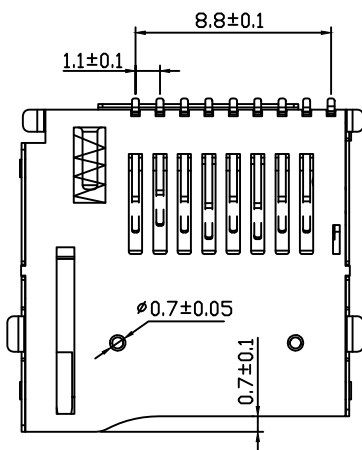


RoHS Compliance

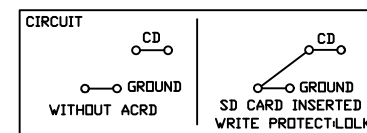
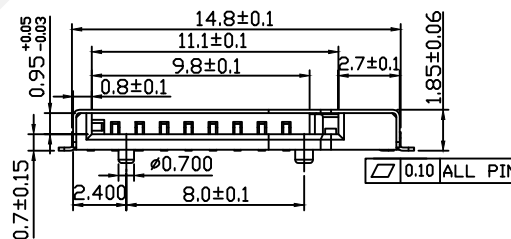
Material:

Insulator: High Temperature Thermoplastic, LCP, UL94V-0.  
 Contact: Copper Alloy T=0.15, Plated 50u" Ni Overall. Plated Au Selective Contact  
 Area Plated 30u"-70u" Sn Over Ni On Solder Area.  
 Shell: T=0.15, Plated 30u" Ni Overall Min. Plated 0.5u" Au Selective Contact Area



Electrical:

Current Rating: 0.5mA max.  
 Voltage Rating: 3.3V  
 Ambient Temperature Range: -25°C ~ +85°C  
 Storage Temperature Range: -25°C ~ +85°C  
 Ambient Humidity Range: 95% R.H. Max.  
 Contact Resistance: 100mΩ Max  
 Insulation Resistance: 1000MΩ Min./500VDC  
 Mating Cycles: 5000 Insertions.  
 Peak Temperature: 260°C ± 0.5°C

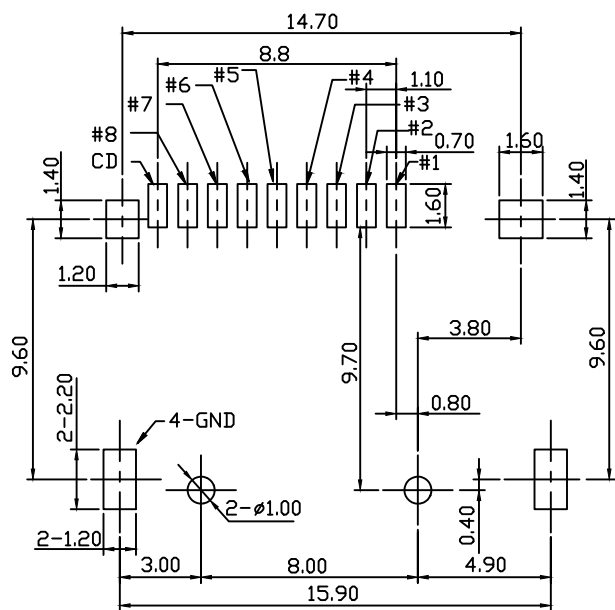


**RHTECP** NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm	SHEET SIZE: A4	SCALE:---	DRWN BY PAN
0~3	3~18	18~50	50~120
±0.12	±0.15	±0.3	±0.5
CHK'D BY FENG		APPR BY ZHAN	

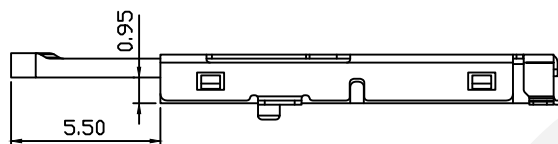
Micro SD Card CONN: PUSH/  
 PUSH, H1.85mm, SMD with CD Pin  
 THIRD ANGLE PROJECTION  
 RHTAYF-003D-H1.9-R

RoHS Compliance

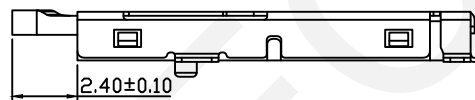


PIN NO.	PIN ASSIGNMENT
1#	DAT2
2#	CD/DAT3
3#	CMD
4#	VDD
5#	CLK
6#	VSS
7#	DAT0
8#	DAT1
9#	CD

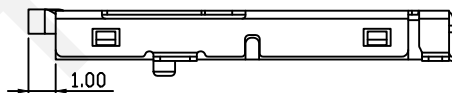
T-Flash Card Insert Drawing:



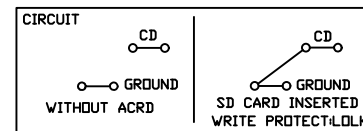
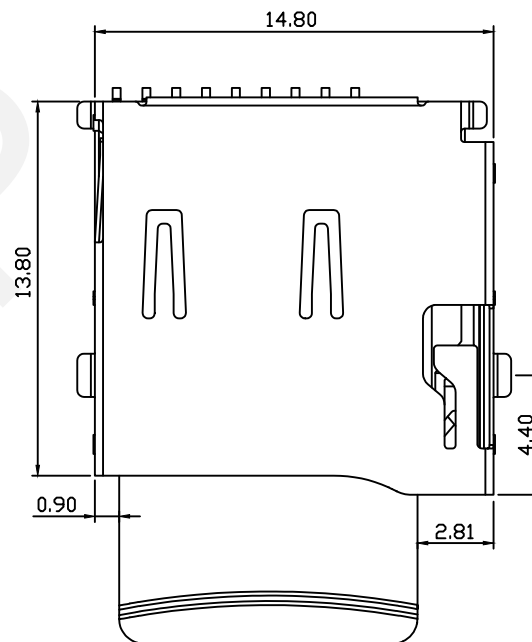
Micro SD Card-Un Lock



Micro SD Card-Lock



Micro SD Card-Push



**RHTECP** NINGBO RHT ELECTRONIC CO.,LTD

UNITS:mm SHEET SIZE: A4 SCALE:--- DRWN BY PAN  
 0~3 3~18 18~50 50~120 CHK'D BY FENG  
 ±0.12 ±0.15 ±0.3 ±0.5 APPR BY ZHAN

Micro SD Card CONN:PUSH/  
 PUSH,H1.85mm,SMD with CD Pin  
 THIRD ANGLE PROJECTION  
 RHTAYF-003D-H1.9-R